

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claims 8 and 18 as follows:

**LISTING OF CLAIMS:**

Claims 1 - 7 (Canceled)

Claim 8. (Currently Amended) A method for manufacturing electronic devices obtained by equipping ~~with electronic component chips on~~ a printed circuit board with electronic component chips ~~and so forth~~, comprising the steps of:

supplying a plurality of electronic component chips in an aligned relationship;  
and cleaning outer surfaces of the electronic component chips;

wherein said step of supplying a plurality of electronic component chips  
comprises the steps of:

supplying a plurality of electronic component chips by a hopper;  
transferring a plurality of electronic component chips by a buffer portion; and  
feeding a plurality of electronic component chips one at a time by a chute  
portion disposed in the rear stage of the buffer portion,

and wherein said step of cleaning outer surfaces of the electronic component  
chips is provided between said step of transferring a plurality of electronic  
component chips by a buffer portion and said step of feeding a plurality of electronic  
component chips by a chute portion.

Claim 9. (Previously Presented) A method according to Claim 8, wherein said step of cleaning outer surfaces of the electronic component chips comprises a process of grinding outer surfaces of electronic component chips.

Claim 10. (Previously Presented) A method according to Claim 9, wherein the process of grinding outer surfaces of electronic component chips is carried out with an abrasive belt and a driving source for driving the abrasive belt.

Claim 11. (Original) A method according to Claim 10, wherein said step of transferring a plurality of electronic component chips is provided with a transferring belt for transferring electronic component chips and the transferring belt serves as well as the abrasive belt.

Claim 12. (Previously Presented) A method according to Claim 8, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

Claim 13. (Previously Presented) A method according to Claim 8, wherein said step of cleaning outer surfaces of the electronic component chips comprises a process of grinding outer surfaces of electronic component chips.

Claim 14. (Previously Presented) A method according to Claim 8, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

Claim 15. (Previously Presented) A method according to Claim 9, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

Claim 16. (Previously Presented) A method according to Claim 10, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

Claim 17. (Previously Presented) A method according to Claim 11, wherein said step of cleaning outer surfaces of the electronic component chips is performed by washing outer surfaces of electronic component chips using a washing liquid.

Claim 18. (Currently Amended) A method for manufacturing electronic devices obtained by at least maintaining electronic component chips on a printed circuit board, comprising the steps of:

supplying a plurality of electronic component chips in an aligned relationship by a chute portion: [[.]] wherein

discharging aligned electronic component chips ~~are taken out~~ one at time from ~~[[a]]~~ the chute portion ~~connected to a buffer portion~~; and

cleaning external electrodes of the electronic component chips.